

| Ref # | Hits | Search Query   | DBs   | Default Operator | Plurals | Time Stamp       |
|-------|------|--|---|------------------|---------|------------------|
| L1    | 353  | (etchant or slurry) same tub\$4 same (CMP or "chemical mechanical polishing")  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/01/08 08:49 |
| L2    | 3297 | (etchant or slurry) and (tub\$4 or nozzle or inlet) and (CMP or "chemical mechanical polishing") and (wafer or substrate)    | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/01/08 08:51 |
| L3    | 353  | (etchant or slurry) same (tub\$4 or nozzle or inlet) same (CMP or "chemical mechanical polishing") same (wafer or substrate) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/01/08 08:52 |
| L4    | 3827 | (etchant or slurry) same remov\$4 same suction\$3  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/01/08 08:53 |
| L5    | 161  | 4 and semiconductor  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/01/08 08:56 |
| L8    | 1422 | (etchant or slurry or solution) same (nozzle or inlet or tube) same wafer same (rins\$3 or wash\$3)                          | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/01/08 08:56 |
| L10   | 766  | 8 and semiconductor and clean\$3   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/01/08 08:59 |
| L11   | 3    | "5722875".pn.  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/01/08 09:02 |